

ABOUT INDUSTRY MEDICAL DEVICES BIG SCIENCE USM SEMICONDUCTORS

ADVANCED CERAMICS

"MAKING THE SMALL PROFITABLE"

TECHNICAL CERAMICS BEYOND THE STANDARD



Nanoker Research specializes in manufacturing technical ceramic components, from custom powder mixtures to the final product.

Nanoker handles every stage of ceramics production, including material selection, processing, sintering, and finishing.

22 People

• 30% of our workforce are experts dedicated to innovating new materials and products

6 patents under exploitation

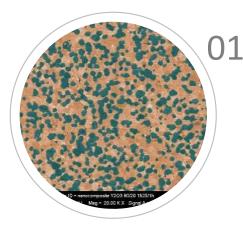
 The patents, owned exclusively by CINN-CSIC, are licensed to Nanoker and encompass innovations in new nanomaterials, nanocomposites, electroconductive ceramics, ultrahard ceramics, and high-thermal conductivity composites





BUSINESS MODEL

We specialize in the manufacture of high-value premium components. Our three key competitive edges are:



Innovation in the design of proprietary materials

Expertise in the synthesis of ceramic materials and blends. Protection of our technology with six active patents.



Leveraging cutting-edge production technologies for optimal results

Adoption of advanced and digital fabrication methods such as spark plasma sintering, pressure casting, and precision green machining..



Expertise in precise, cost-effective manufacturing

Precision machining of pre-sintered green bodies.

Efficient production of intricate designs.

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NANOKER PROPRIETARY MATERIALS

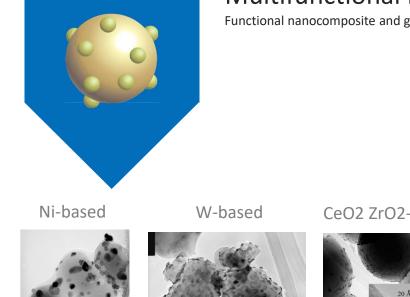
Oxides and metal-ceramic nanocomposite powders production Line

naneker

ADVANCED CERAMICS

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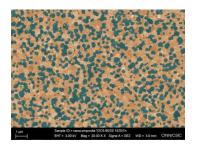
From commercial Powders & Precursors To Nanostructured Raw Materials & Nanocomposites



100 nm

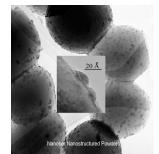


Functional nanocomposite and glass-ceramic powders.



SEMICONDUCTORS

CeO2 ZrO2-based



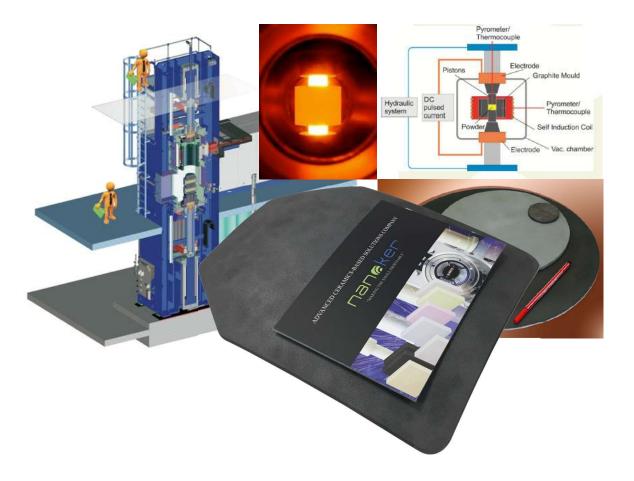
Advanced ceramics

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SEMICONDUCTORS

NANOKER ADVANCED PRODUCTION TECHNOLOGIES



Spark Plasma Sintering

The most advanced production technology for ceramic, metal, composites and advanced nanomaterials and nanocomposites

Alumina-TiC-SiCw, Zirconia TZP-TiN Electroconductive tough ceramics

Alumina-SiCw, B₄C, SIC Low density, high hardness

Graphite-Mo, Cu-Diamond, KALMAN, KBNC Heat Sink composites

Alumina-LAS, LAS-SiC, LAS-SiC-CNF Very low or tailored CTE

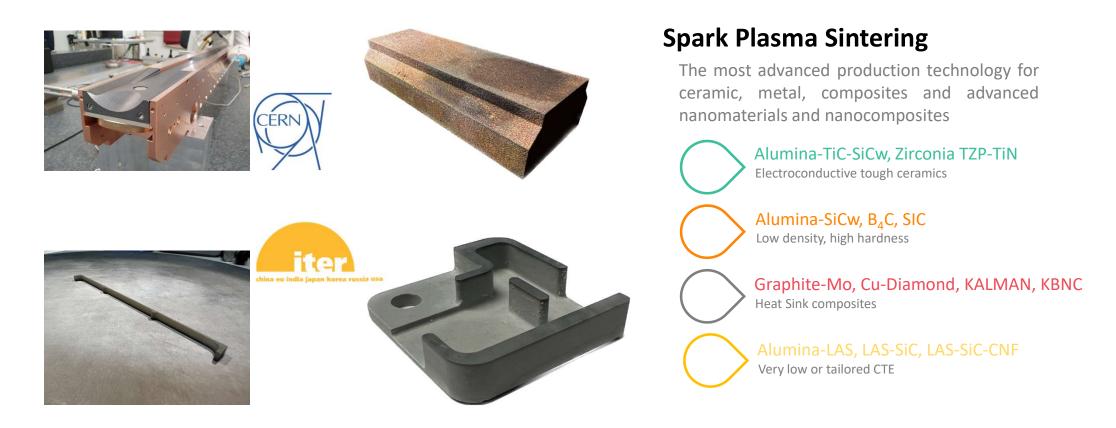


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NANOKER ADVANCED PRODUCTION TECHNOLOGIES





NANOKER UNIQUE KNOW-HOW IN DIRECT MANUFACTURING



CAD-CAM from green bodies

4 axis NC of cold isostatic pressed bars



CAD-CAM NC of complex shaped parts

Complex structures can be produced by machining cold isostatic pressed bars and subsequently sintered at high temperatures



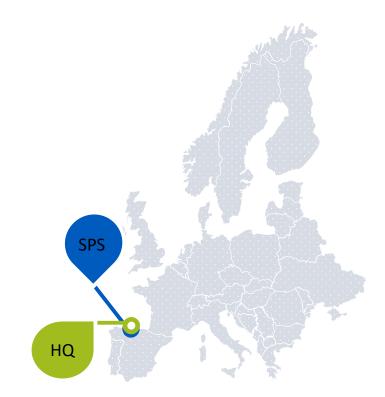


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SEMICONDUCTORS

PRODUCTION FACILITIES



Headquarters

Olloniego, Asturias, Spain 1500 m² Industrial and bioceramics



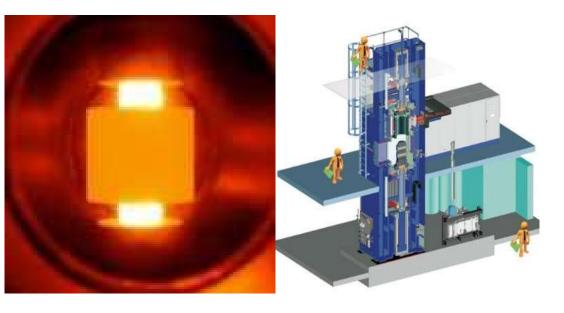
SPS / R&D materials Sotrondio, Asturias, Spain

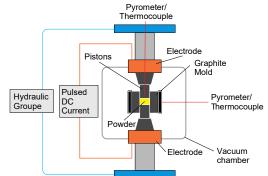
1200 m² Spark Plasma Sintering Big science



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BIG SCIENCE ⇒ SPECIAL MATERIALS ⇒ SPARK PLASMA SINTERING





Hybrid HP-SPS sintering, FAST



Thermal management

Boron nitride composites

<u>UHTCMC's (Ultra-high Tª</u> <u>ceramics)</u>



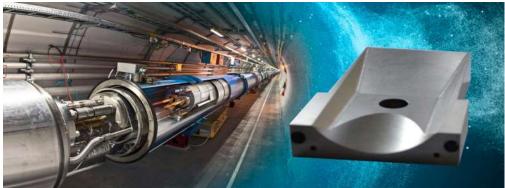
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THERMAL MANAGEMENT



Physical properties

Parameters



Primary collimator. Picture courtesy of CERN

g/cm³ 2.57 Density **Flexural Strength** MPa 102.1 | 16.9 Flexural Strain to rupture µm/m 2580 | 5900 69.7 5.5 Young Modulus GPa Thermal conductivity (@20°C/300°C) W/m·k 650/310 45/23 Thermal Diffusivity (@20°C/300°C) mm²/s 390/110 27/8 CTE average (20-1000°C) 10-6K-1 6.5 CTE *2 (20-1000°C) 10-6K-1 2.4 | 14.7 Specific heat J/g·K 0.65 Electrical conductivity MS/m 0.8 Dimensional stability % 0 0.1

Units

X,Y | Z *1

All properties measured at 20°C unless otherwise stated

¹¹ XY - Parallel to the grain direction; Z - Perpendicular to the grain direction ¹² CTE adjustability according to chemical composition

KTM-650 GRAPHITE-METAL CARBIDE COMPOSITES

Electrically conductive

- TC (in plane) 650 W/M K
- Anisotropic. Homologated by CERN for primary collimators, specially approved for outgassing conditions.

Other applications

Heat sinks for electronics

Thermal dissipation with a CTE-matched with Si, SiC, GaN, and low density.

Rocket Nozzles

Outperforming the results of conventional graphitic material

1 2003 4 5 - 6 7 6 9 10 10 12 Block for collimator (position tolerance of 5 micron)



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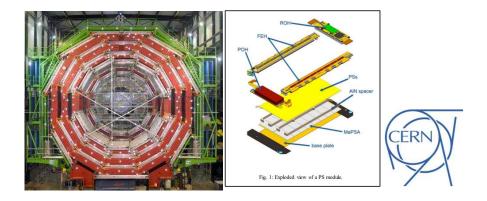
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KALMAN (MACHINABLE AIN)

	Machinable Alumin	um Ni	tride
	Physical properties		
1 Panana and	Parameters	Units	Value
	Density	g/cm ³	2.94
	Flexural Strength	MPa	261
	Compressive strength	MPa	737
	Hardness	HB 2.5/62.5	285
Printin Piz-I	Porosity	%	0
	Thermal Expansion Coefficient (@20-400°C) 10 ⁻⁶ ·K ⁻¹	5.2
ele ele	Thermal Conductivity (@100°C)	W/m-K	99.2
TI-II APEL	Volume Resistivity (@25°C, DC)	Ω·cm	5-10"
ED- CA	Dielectric Strength** (50 Hz, AC)	kV/mm	26.7
	 All properties measured at 20°C unless otherwise s ** Measured in a wall thickness of 2 mm 	tated	
		10	-



PURE AIN FRAMES CMS DETECTOR - CERN





F4E-OPE-1150; "Final Design and Supply Of In-Divertor Electrical Services (IDES) and Supply of In-Vessel Supports (IVS) for Mineral Insulated (MI) Cabling for ITER Diagnostics Systems"

- Electrical insulator
- Isotropic
- TC 100 W/m·K Homologated by ITER
- Machinable with WC tools

IT 4671: "Supply of spacers and stiffeners of AIN machined by micro-water jet cutting"

Material: Pure AIN. Scope: 61.000 pieces

- High electrical insulation
- CTE 5 ppm/ºC (matching Si)
- 180 W/m·K
- High rigidity



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BORON NITRIDE COMPOSITES



Picture courtesy of Nasa. HERMeS: NASA's SPT Thruster. Inner and outer wall of BN composite.



Physical properties				
Parameters	Units	Value		
Density	g/cm ³	2.90		
Strength (3 point bending)	MPa	160		
Hardness Knoop	Kg/mm ²	85		
Thermal conductivity (in-plane XY)	W/m·k	50		
Thermal conductivity (out-plane Z)	W/m·k	10		
Thermal Expansion Coefficient (XY)	10 ⁻⁶ K ⁻¹	4.0		
Maximum use temperature (Oxidizing/Inert)	°C	800/1500		

*All properties measured at 20°C unless otherwise stated

Blanks and properties of boronnitride composites obtained by Nanoker.

High Temperature Refractory BN Composites

A top-end boron nitride composite with extreme resistance to thermal shock up to 1500°C under inert or vacuum environments. High refractoriness thanks to the formulation of specific compositions.



Dielectric wall of Hall-effect Thruster An ideal material for critical parts of the thruster in

electrical propulsion systems

Components for non-metal ferrous industries



ZrB2-SiC-Cf ULTRA HIGH TEMPERATURE CERAMIC COMPOSITES (UHTCMC)

C3HARME, Next generation Ceramic Composites for Combustion HARsh environMEnts and space

- Thermal Shock Resistant
- Ablation Resistant
- High Temperature Resistance (>2000°C)

Property	Value	Comment
Vol % of fibers	up to 50%	Conventional ceramic processing enables to incorporate high amount of short fibers
Density (kg/m³)	3.9 - 4.2	Variation of porosity and fiber volume fraction impact on the final density
Fracture toughness (RT)	4 - 5	The presence of the fibers improves the damage tolerance of the UHTC matrix
CTE (10-6 K-1) (20-1500 °C)	4.7 - 5.5	CTE is reduced as compared to the UHTC matrix
Thermal conductivity (W/m K), 20-1500°C	50-33	Efficient heat dissipation is guaranteed by high thermal conductivity up to high temperatures
Thermal diffusivity (mm²/s) (20-1950°C)	sivity (mm²/s) 22-7 Measured close to 2000°C. Material is completely stable up to this temperature	
Bending strength (MPa)	130-140	This value depends on fiber amount and length.





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